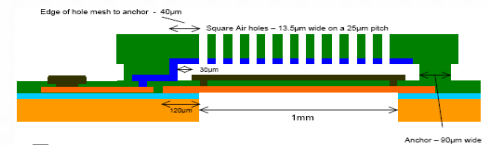
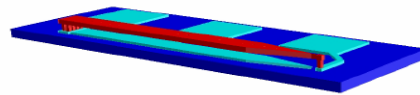
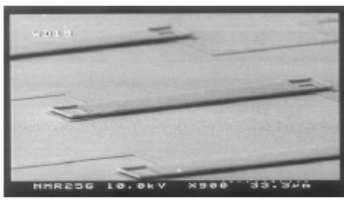


Modelling Effects of Packaging on MEMS, WP2 & WP4 Round Robin Modelling Study, WP2 Activities

Objectives:

- Fabrication, test and characterisation of three micromechanical test structures; FE modelling of structures
- Comparison of simulation results across a range of tools - benchmarking
- Identification of parameters required in establishing common data formats
- Characterisation of 3 die attach materials
- Simulation of the effects of packaging on MEMS
- Investigation of suitability/limitations of modelling tools with regard to packaging of MEMS devices



**Test Structures and Packages
 for Model Benchmarking**

WP2 Partners involved:

Tyndall, QinetiQ, ULANC, HWU, IMT, BUTE, POLIMI, ULG, WUT, IZM

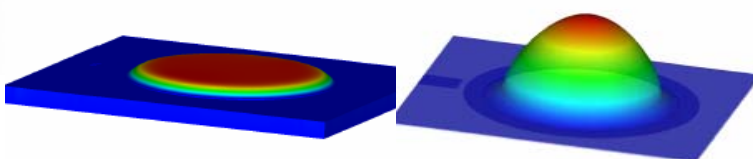
Offer to industry:

- Validated Behavioural models for Packaged MEMS
- Benchmarked and Standardised Methodology for Simulating Packaged MEMS

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Project status: Kicked off October 2005



**Displacement of Microphone Membrane
 under Residual Stress**

